

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): A resin composition comprising a resin crystallization promoter comprising vapor grown carbon fibers, each fiber filament of the carbon fibers having a diameter of 0.001 μm to 5 μm and an aspect ratio of 5 to 15,000,

the fibers having undergone a graphitization at 1,500°C or higher, and

the resin composition being obtained by kneading the crystallization promoter with a resin, and subsequently subjecting the resultant mixture to annealing at a temperature of from 55°C higher than the glass transition point of the resin to a temperature 75°C higher than the glass transition point of the resin, and

the resin being an amorphous thermoplastic resin.

2. (canceled).

3. (previously presented): The resin composition as claimed in claim 1, wherein the vapor grown carbon fibers contain boron in an amount of 0.001 to 5 mass%.

4 to 6. (canceled).

7. (currently amended 1): The resin composition as claimed in claim 15, wherein the amorphous thermoplastic resin is a resin containing a polymer including a structural unit having an aromatic group as a repeating unit.

8. (currently amended): The resin composition as claimed in claim 15, wherein the amorphous thermoplastic resin is any species selected among polystyrene, polycarbonate, polyarylate, polysulfone, polyetherimide, ~~polyethylene terephthalate~~, polyphenylene oxide, polyphenylene sulfide, ~~polybutylene terephthalate~~, ~~polyimide~~, and polyamide-imide ~~and polyether ether ketone~~; or a mixture thereof.

9. (previously presented): The resin composition as claimed in claim 1, which, when subjected to differential scanning calorimetry (DSC), exhibits an endothermic/exothermic peak which is not associated with change in mass at a temperature other than the glass transition point of the resin.

10. (previously presented): The resin composition as claimed in claim 1, which, when subjected to differential scanning calorimetry (DSC), exhibits an endothermic/exothermic peak attributed to melting or crystallization of the composition, wherein the peak is higher or the peak shifts to a higher temperature region, as compared with the case of a resin composition which does not contain the resin crystalline promoter.

11. (previously presented): The resin composition as claimed in claim 1, which, when subjected to X-ray diffractometry, exhibits a peak attributed to the resin, and a peak attributed to orderly arrangement of a resin structure.

12. (previously presented): The resin composition as claimed in claim 1, wherein, in X-ray diffractometry, the half width of the band of the diffraction angle (2θ) corresponding to a peak attributed to orderly arrangement of a resin structure is 5° or less.

13. (previously presented): The resin composition as claimed in claim 1, wherein the content of the resin crystallization promoter is 0.1 to 80 mass%.

14. (canceled).

15. (previously presented): An electrically conductive material comprising the resin composition as claimed in claim 1.

16. (previously presented): A thermally conductive material comprising the resin composition as claimed in claim 1.

17. (previously presented): A material exhibiting tribological characteristics comprising the resin composition as claimed in claim 1.

18. (previously presented): A mechanism part comprising the resin composition as claimed in claim 1.